

In re Application of: Jarvis, et al.

Serial No.: 09/828,715

Filed: April 6, 2001

Confirmation No.: 5602

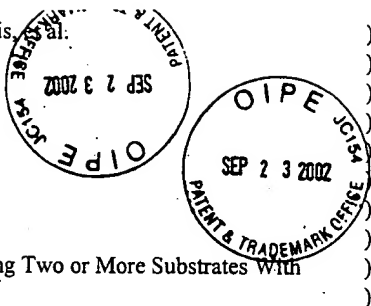
Title: A Method of Joining Two or More Substrates With  
a Seam

Commissioner for Patents  
U.S. Patent and Trademark Office  
Washington, DC 20231

Group Art Unit: 1772

Examiner: J. Rhee

Our Account No.: 04-1403



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**AMENDMENT**

This is a response/amendment/letter in the above-identified application and includes the herewith attachment of same date and subject which is incorporated hereinto by reference and the signature below is to be treated as the signature to the attachment in absence of a signature thereto.

Fee requirements (if any) have been calculated as shown below:

| Claims remaining after amendment   | Highest number previously paid for | Present Extra | Additional Fee |
|--|------------------------------------|---------------|----------------|
| Total Effective Claims 34  | minus 40                           | = 0 x \$18 =  | \$ 0.00        |
| Independent Claims 3   | minus 0                            | = 0 x \$84 =  | \$ 0.00        |
| If amendment enters proper multiple dependent claim(s) into this application for first time, add \$270.00 (per application)  |                                    |               | \$             |
| Since Official Action set an original due date of <u>N/A</u>   |                                    |               |                |
| PETITION is hereby made for an extension to cover the date this response is filed for which the requisite fee is enclosed (1 month \$110; 2 months \$400; 3 months \$920; 4 months \$1440) |                                    |               | \$ 0.00        |
| If Terminal Disclaimer enclosed, add Rule 20(d) Official Fee (\$110.00)  |                                    |               | \$             |
| <b>SUBTOTAL:</b>   |                                    |               | \$ 0.00        |
| If "small entity" verified statement filed <input type="checkbox"/> previously, <input type="checkbox"/> herewith, enter one-half (1/2) of subtotal and <u>subtract</u>                    |                                    |               | \$             |
| <b>TOTAL:</b>  |                                    |               | \$ 0.00        |
| Other: <u>Information Disclosure Statement w/ two (2) cited references</u>   |                                    |               | \$             |
| <b>TOTAL FEE ENCLOSED:</b>   |                                    |               | \$ 0.00        |

The Commissioner is hereby authorized to charge any fee specifically authorized hereafter, or any fees in addition to the fee(s) filed, or asserted to be filed, or which should have been filed herewith or concerning any paper filed hereafter, and which may be required under Rules 16-18 (deficiency only) now or hereafter relative to this application and the resulting official document under Rule 20, or credit any overpayment, to our Account No. shown in the heading hereof for which purpose a duplicate copy of this sheet is attached. This statement does not authorize charge of the issue fee in this case.

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**DORITY & MANNING**

**ATTORNEYS AT LAW, P.A.**

By Atty: Jason W. Johnston Reg. No.: 45,675

Signature: [Signature]

I hereby certify that this correspondence and any referenced attachment and fee are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, DC 20231, on September 18, 2002.

Lynn Watkins

(Typed or printed name of person mailing paper or fee)

(Signature of person mailing paper or fee)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AMENDMENT

Dear Sir:

In response to the Office Action dated June 19, 2002, please amend the above-captioned application as follows:

IN THE CLAIMS:

Please cancel claims 2-4 and 38-40.

Please amend claims 1, 19-20, 22, 26-27, 29, and 32-33 to read as follows (See also Appendix A):

1. (Amended) A method of forming a seam between substrates comprising:  
providing a first substrate having an upper surface and a lower surface, said  
upper and said lower surfaces of said first substrate defining at least one edge;  
providing a second substrate having an upper surface and a lower surface, said  
upper and said lower surfaces of said second substrate defining at least one edge;

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